

L Number	Hits	Search Text	DB	Time stamp
1	2528010	die chip semiconductor ic (integrated adj circuit) dice	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:43
2	1843861	sheet (silicone with rubber) silicone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:43
3	351061	heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:44
4	1948566	resin polyamide polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:44
5	190	(die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide) same "5"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:46
6	856	(die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:47
7	339	((die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:48

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7	339	((die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:48
6	856	((die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:48
8	223	((die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)) and solder) and ((silicone with rubber) silicone rubber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:48

L Number	Hits	Search Text	DB	Time stamp
1	247243	polyamide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 10:19
2	223	((die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)) and solder) and ((silicone with rubber) silicone rubber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 10:20
3	257783	polyamide amd (((die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)) and solder) and ((silicone with rubber) silicone rubber))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 10:20
4	44	polyamide and (((die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)) and solder) and ((silicone with rubber) silicone rubber))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 10:20